

#5/Response  
(NE)PATENT APPLICATION  
Serial No. 10/043,709

3/12/03

Hago

**CERTIFICATE OF FACSIMILE**

I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being deposited via facsimile no. (703) 872-9319 on \_\_\_\_\_.

Signed: \_\_\_\_\_

Kathy Dixon

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re : Kuo-Yu Chou, et al. : Docket No. 67,200-603

Serial No. : 10/043,709 : Art Unit No. 2814

Filing Date : January 9, 2002 : Examiner: Le, Thao X

Paper No. : 5 : Confirmation No: 6454

Invention Title: **A SINGLE LAYER WIRING BOND PAD WITH OPTIMUM  
AL FILM THICKNESS IN CU/FSG PROCESS FOR DEVICES  
UNDER PADS**

**RESPONSE TO FINAL OFFICE ACTION**

FAX RECEIVED

MAR 10 2003

TECHNOLOGY CENTER 2800

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

Sir:

In response to the Official Action dated January 29, 2003 (Paper No. 4), Applicants respectfully request reconsideration and further examination of all claims presented.